Nch 30V 7A Power MOSFET

V_{DSS}	30V
R _{DS(on)} (Max.)	28mΩ
I _D	±7A
P _D	2.0W

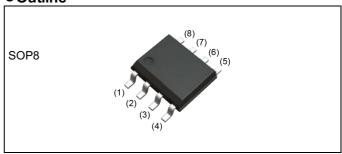
● Features

- 1) Low on-resistance
- 2) Small Surface Mount Package (SOP8)
- 3) Pb-free lead plating; RoHS compliant
- 4) Halogen Free

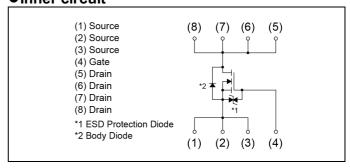
Application

Switching

Outline



●Inner circuit



Packaging specifications

	Jing opcomoducino	
	Packing	Embossed Tape
Type	Reel size (mm)	330
	Tape width (mm)	12
	Quantity (pcs)	2500
	Taping code	ТВ
	Marking	RXH070N03

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	30	V
Continuous drain current	I _D	±7	А
Pulsed drain current	I _{DP} *1	±18	А
Gate - Source voltage	V_{GSS}	±20	V
Dower discinction	P _D *2	2.0	W
Power dissipation	P _D *3	1.4	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Deremeter	Symbol	Values			Linit
Parameter		Min.	Тур.	Max.	Unit
Thermal registance junction, ambient	R _{thJA} *2	-	1	62.5	°C/W
Thermal resistance, junction - ambient	R _{thJA} *3	-	1	89.2	°C/W

● Electrical characteristics (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	30	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	34.15	-	mV/°C	
Zero gate voltage drain current	I_{DSS} $V_{DS} = 30V, V_{GS} = 0V$		1	-	1	μA	
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	1	-	±10	μA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10V, I_{D} = 1mA$	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	-2.34	-	mV/°C	
		V _{GS} = 10V, I _D = 7A	-	20	28		
Static drain - source on - state resistance	R _{DS(on)} *4	V _{GS} = 4.5V, I _D = 7A	-	25	35	mΩ	
		$V_{GS} = 4.0V, I_D = 7A$	1	28	39		
Gate resistance	R _G f = 1MHz, open drain		1	4.0	1	Ω	
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = 10V, I _D = 7A	4.5	-	-	S	

^{*1} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*2} Mounted on a ceramic board (30×30×0.8mm)

^{*3} Mounted on a FR4 (25×25×0.8mm)

^{*4} Pulsed

●Electrical characteristics (T_a = 25°C)

Darameter	Cymah ol	Conditions	Values			Unit	
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Orill	
Input capacitance	C _{iss}	V _{GS} = 0V	-	390	-		
Output capacitance	C _{oss}	V _{DS} = 10V	-	150	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	70	-		
Turn - on delay time	t _{d(on)} *4	V _{DD} ≈ 15V,V _{GS} = 10V	-	7	-		
Rise time	t _r *4	I _D = 3.5A	-	30	-	-	
Turn - off delay time ${\mathsf t_{\mathsf d(\mathsf off)}}^{*4}$		$R_L \simeq 4.3\Omega$	-	30	-	ns	
Fall time	t _f *4	$R_G = 10\Omega$	-	8	-		

• Gate charge characteristics $(T_a = 25^{\circ}C)$

	\ u	,				
Parameter	Cy week ol	Conditions	Values			Unit
raianetei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Qg*4	V _{DD} ≃ 15V,	-	5.8	-	
Gate - Source charge	Q _{gs} *4	I _D = 7A,	-	1.5	-	nC
Gate - Drain charge	Q _{gd} *4	$V_{GS} = 5.0V$	-	2.3	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Darameter	Cumbal	Conditions	Values			l leit	
Parameter	Parameter Symbol		Min.	Тур.	Max.	Unit	
Continuous forward current	I _S	T = 25°C	-	-	1.6	Α	
Pulse forward current	I _{SP} *1	T _a = 25℃	-	-	18	Α	
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = 7A	-	-	1.2	V	

Fig.1 Power Dissipation Derating Curve

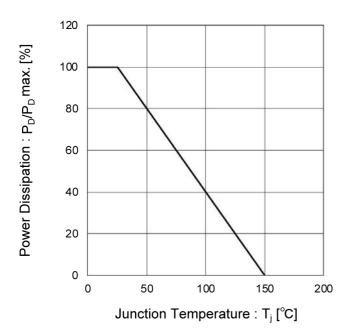
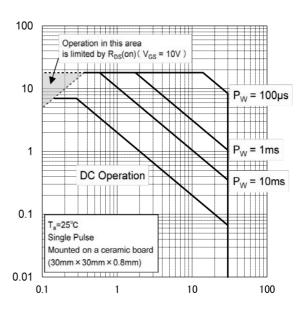


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

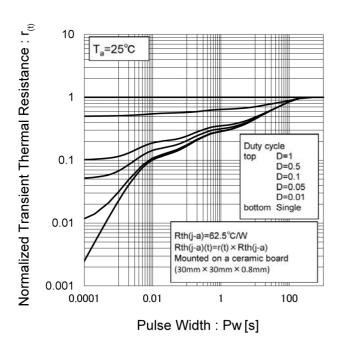
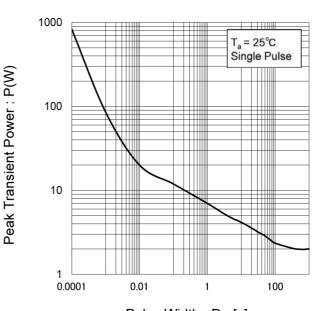


Fig.4 Single Pulse Maximum Power dissipation



Pulse Width : Pw [s]

Fig.5 Typical Output Characteristics(I)

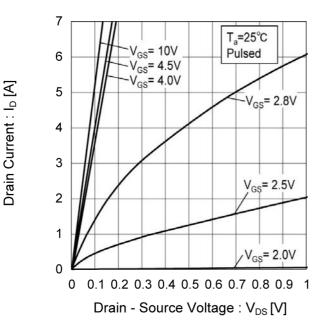


Fig.6 Typical Output Characteristics(II)

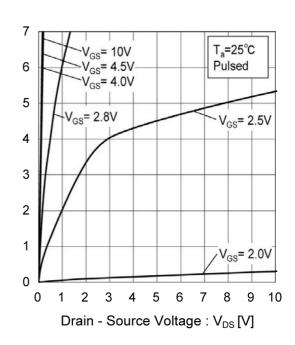
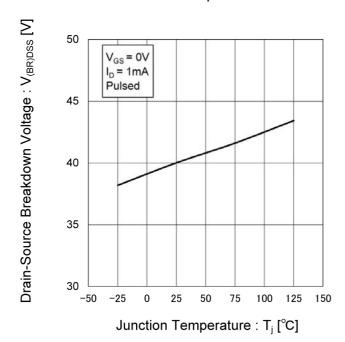


Fig.7 Breakdown Voltage vs.

Junction Temperature



Drain Current : I_D [A]

Fig.8 Typical Transfer Characteristics

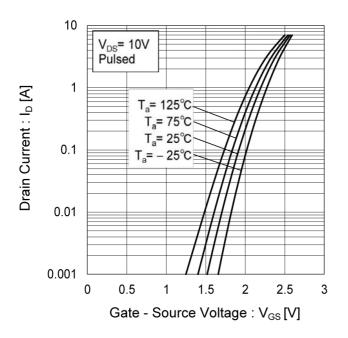


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

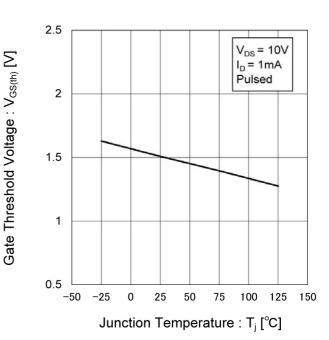


Fig.10 Forward Transfer Admittance vs.
Drain Current

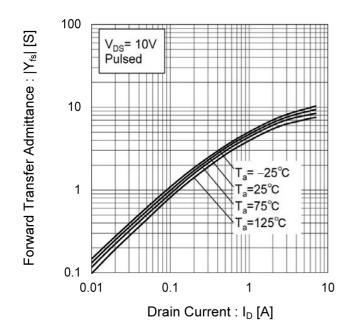


Fig.11 Drain Current Derating Curve

120 100 Drain Current Dissipation 80 : I_D/I_Dmax. [%] 60 40 20 0 -25 0 25 50 75 100 125 150 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

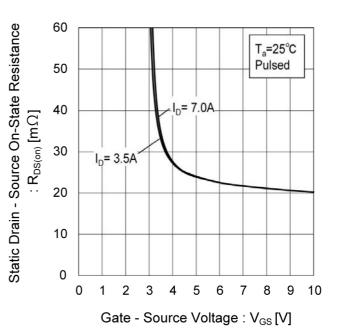


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

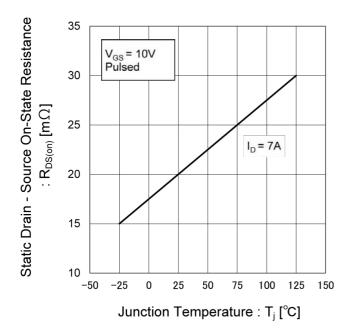


Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

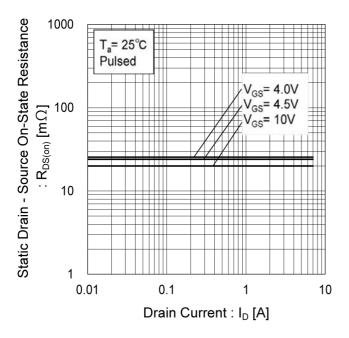


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

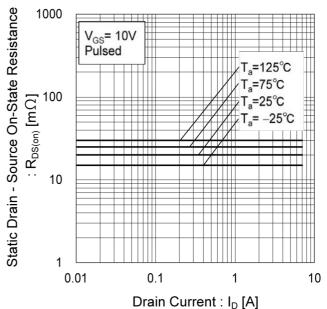


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

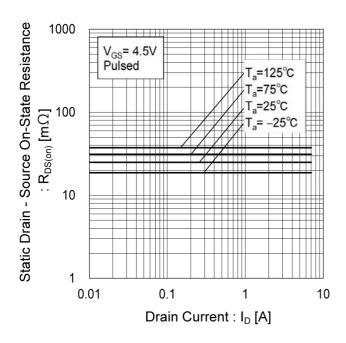


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current (IV)

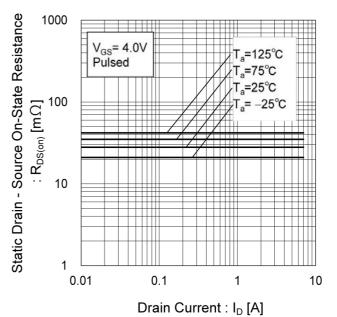


Fig.18 Typical Capacitance vs.

Drain - Source Voltage

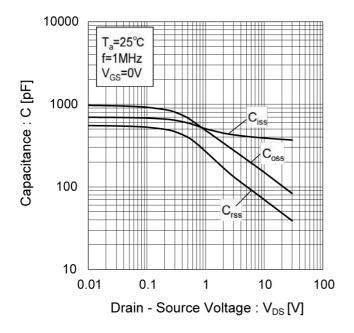


Fig.19 Switching Characteristics

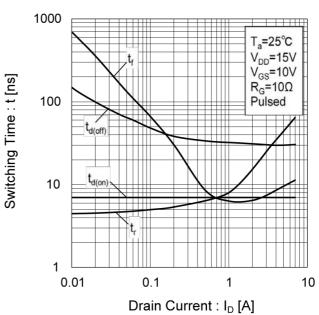


Fig.20 Dynamic Input Characteristics

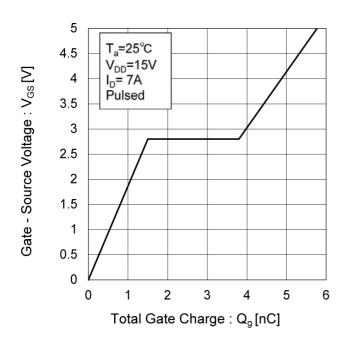
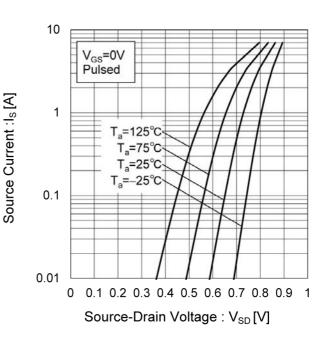


Fig.21 Source Current vs.

Source Drain Voltage



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

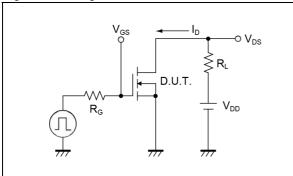


Fig.2-1 Gate Charge Measurement Circuit

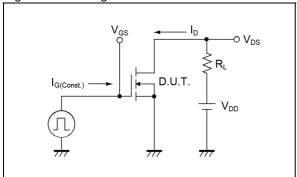


Fig.1-2 Switching Waveforms

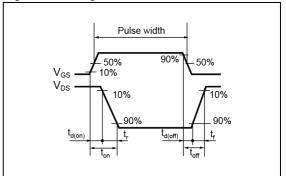
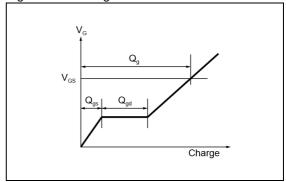
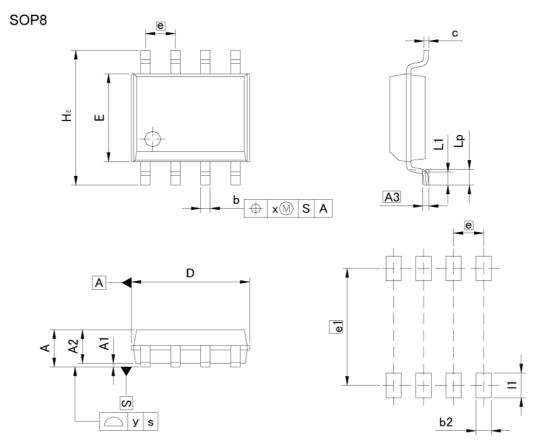


Fig.2-2 Gate Charge Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	<u> </u>	1.75	=:	0.069
A1	0.	15	0.0	06
A2	1.40	1.60	0.055	0.063
A3	0.	25	0.0	10
b	0.30	0.50	0.012	0.020
С	0.10	0.30	0.004	0.012
D	4.80	5.20	0.189	0.205
E	3.75	4.05	0.148	0.159
е	1.	27	0.050	
HE	5.70	6.30	0.224	0.248
L1	0.40	0.60	0.016	0.024
Lp	0.65	0.85	0.026	0.033
x	0.	0.15		06
у	0.	0.10		104
DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	-2	0.65	7 2	0.026

Dimension in mm/inches

e 1



0.045

0.203

1.15

5.15

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CL ACCTI
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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Notice-PGA-E Rev.004

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